

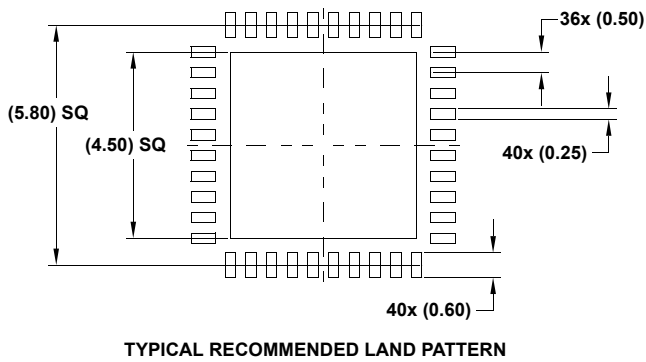
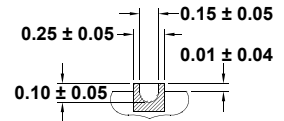
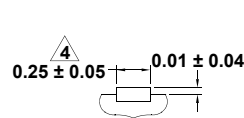
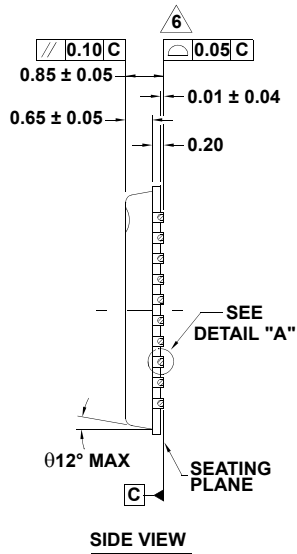
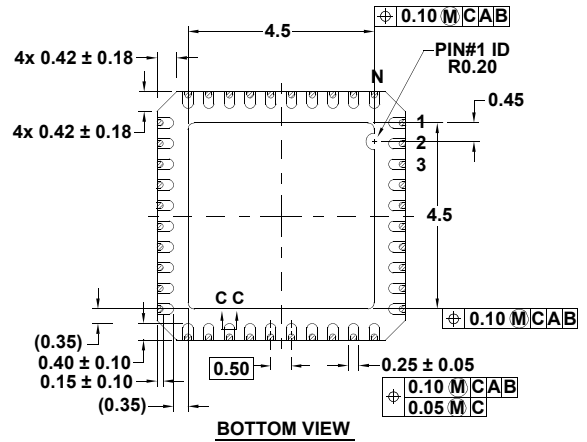
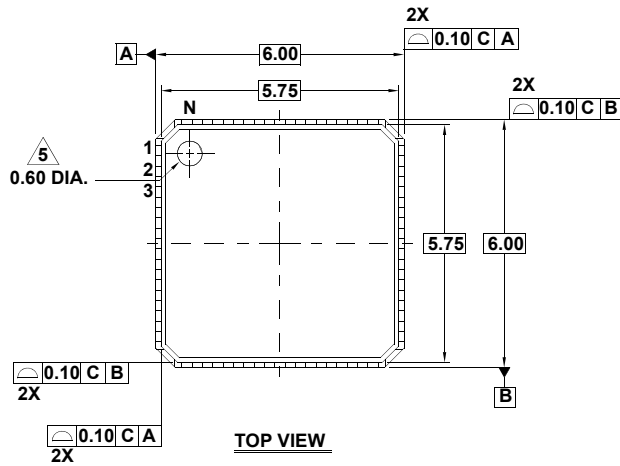
Plastic Packages for Integrated Circuits

Package Outline Drawing

L40.6x6C

40 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN WITH WETTABLE FLANK)

Rev 1, 1/14



NOTES:

- Dimensions are in millimeters.
Dimensions in () for Reference Only.
- Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
- Unless otherwise specified, tolerance : Decimal ± 0.05
- Dimension applies to the plated terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- Reference document: JEDEC MO220